

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Arvind Chandrasekaran	05/05/2009
RECEIVING PARTY DATA	
Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
Internal Address:	Patent Department
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13282712
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ATTORNEY DOCKET NUMBER:	090606D1
NAME OF SUBMITTER:	Michelle Gallardo
Total Attachments: 2 source=090606D1_REC_as-filed_09-22-12#page1.tif source=090606D1_REC_as-filed_09-22-12#page2.tif	

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ASSIGNMENT

TO WHOM IT MAY CONCERN:

For the sum of One Dollar and other valuable consideration to us in hand paid, receipt of which is hereby acknowledged, be it known that I,

Arvind Chandrasekaran, a citizen of India, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of San Diego, California.

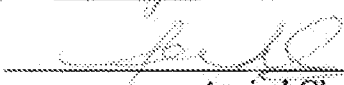
have sold, assigned and transferred and by these presents do sell, assign, transfer and set over unto QUALCOMM Incorporated, a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, its successors, legal representatives, or assigns, the entire right, title and interest in and to a certain invention relating to **Panelized Backside Processing for Thin Semiconductors** by me devised and the application for United States Patent therefore filed in the United States Patent and Trademark Office on May 7, 2009, and assigned Serial No. 12/437,168, and all original and reissue patents granted thereof, and all divisions, continuations and continuations-in-part thereof, including the subject matter of any and all claims which may be obtained in every such patent, and all foreign rights to said invention, and covenant that I have full right to do so, and agree that I will communicate to said corporation or its representatives all facts known to me respecting said invention, whenever requested, and testify in any legal proceedings, sign all lawful papers, make all rightful oaths and generally do everything possible to aid said corporation, its successors, assigns and nominees, to obtain and enforce proper patent protection for said invention in all countries.

ASSIGNMENT

Panelized Backside Processing for Thin Semiconductors

The Commissioner of Patents and Trademarks is requested to issue the Letters Patent which may be granted for said invention or any part thereof unto said corporation in keeping with this Assignment.

Done at San Diego, California this 5 day of May, 2009.



Arvind Chandrasekaran